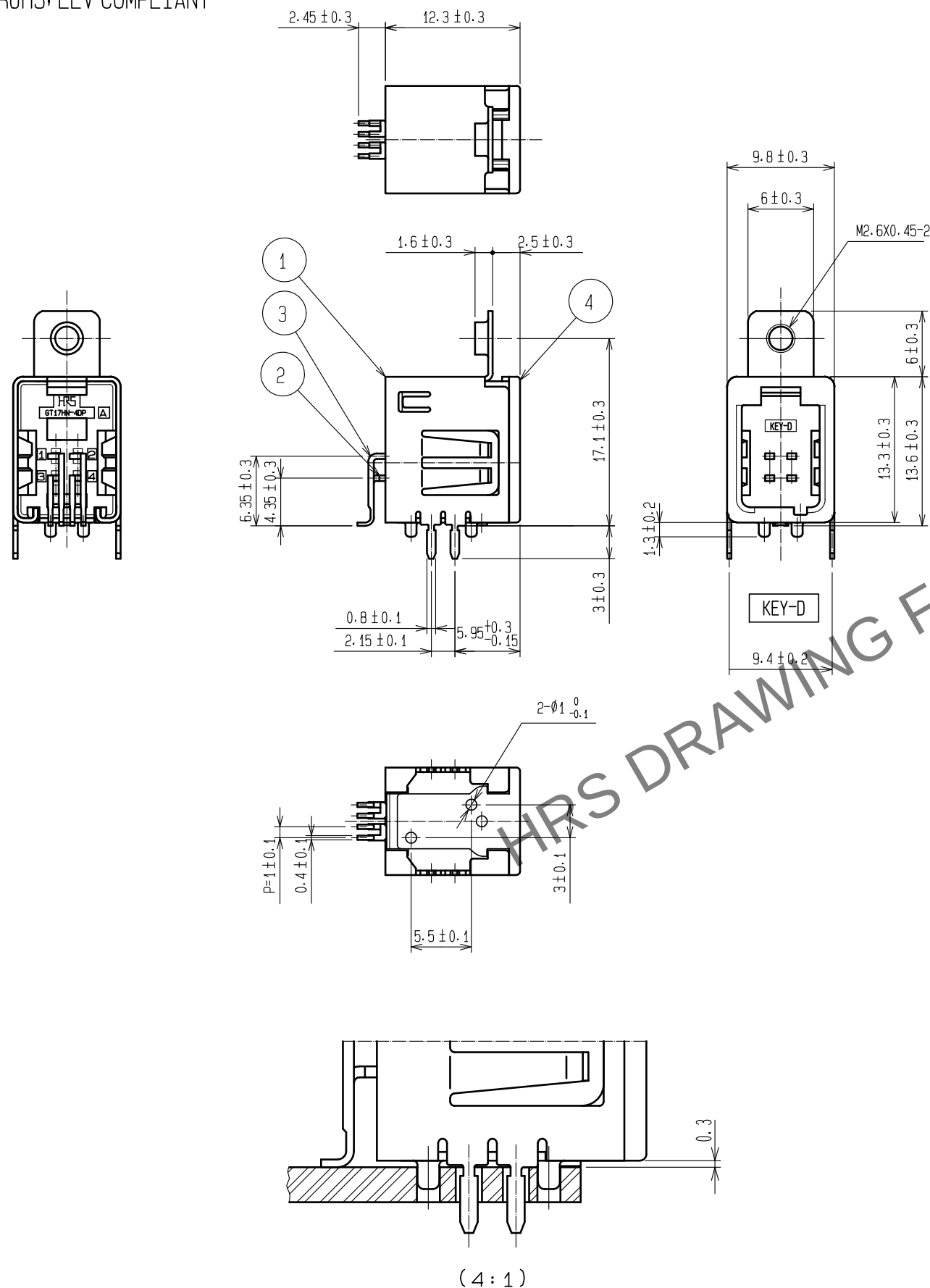


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RoHS, ELV適合品

RoHS, ELV COMPLIANT



Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.

Note2. The temperature indicates the board surface temperature on the connector lead area.

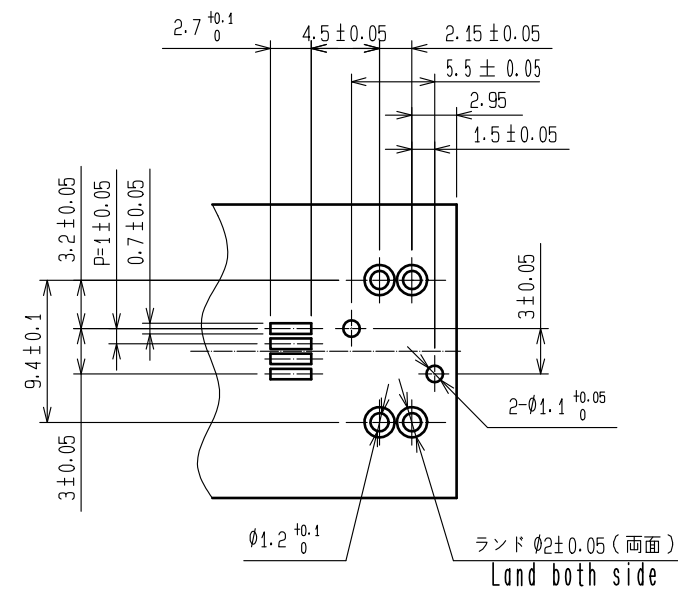
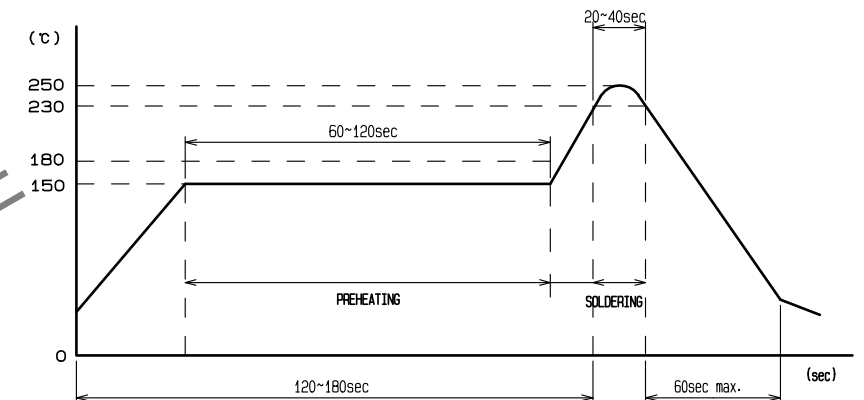
Note3. Hand soldering: 280~300℃, 2s max.

Note4. Coplanarity: 0.1 max.

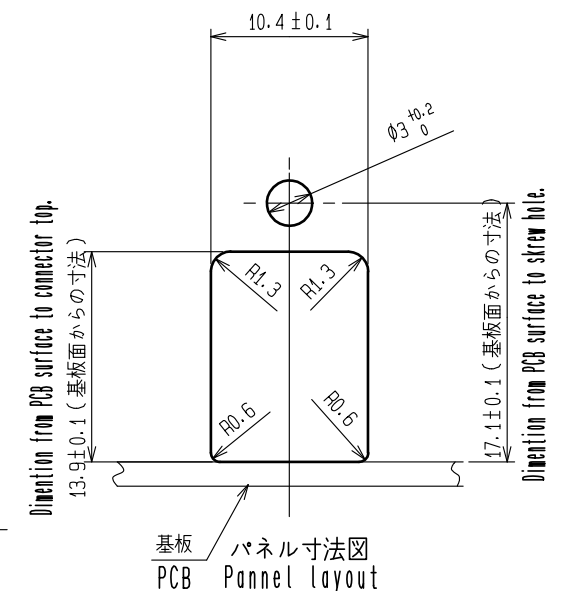
Note5. Recommended thickness of PCB: 1.6mm.

5. 推奨基板厚: 1.6mm

RECOMMENDED REFLOW PROFILE	
IR reflow condition	IR リフロー条件
Preheating area 150℃ for 60 to 120 seconds	予備加熱: 60~120秒, 150℃
Peak temperature: 250℃	ピーク温度: 250℃
Soldering area 235±5℃ or 10 seconds max.	リフロー温度: 230~240℃, 10秒以内
230℃ min. for 20 to 40 seconds	230℃以上: 20~40秒



基板推奨寸法図
Recommended PCB layout



2	BRASS	TIN PLATING	5	PS	TRAY NATURAL
1	COPPER ALLOY	TIN PLATING	4	PPS	BLACK
NO.	MATERIAL	FINISH . REMARKS	3	BRASS	TIN PLATING
UNITS mm		SCALE 2 : 1	NO.	MATERIAL	FINISH . REMARKS
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	APPROVED : KI. HIROKAWA	20200409	DRAWING NO.	EDC-168956-55-00	
	CHECKED : EJ. WAKATSUKI	20200408	PART NO.	GT17HN-4DP-2H(D)(55)	
	DESIGNED : TS. KUBOTA	20200325	CODE NO.	CL767-0276-7-55	
	DRAWN : YK. MITSUISHI	20200319			

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